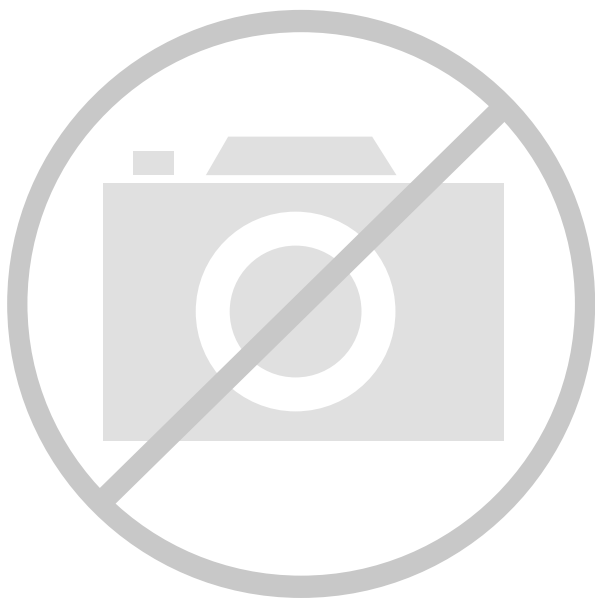




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Understanding **Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	28750
Number of Logic Elements/Cells	115000
Total RAM Bits	7987200
Number of I/O	660
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BCBGA, FCBGA
Supplier Device Package	1152-CFCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga115ep1-5fc1152c

The diagram illustrates the internal structure of a Slice, which is a fundamental building block in an FPGA. It consists of two LUT4 & CARRY blocks, two FF/Latch blocks, and various control and data signals.

Inputs:

- From Routing:** A1, B1, C1, D1, M1, M0, A0, B0, C0, D0.
- Control Signals selected and inverted per slice in routing:** CE, CLK, LSR.
- FCI from Slice/PFU, FCO from Different Slice/PFU:** Signals entering and leaving the slice for configuration and control.

Internal Components:

- LUT4 & CARRY Blocks:** Each block takes four data inputs (A, B, C, D) and produces a function output (F) and a carry output (CO). The carry input (CI) is also provided.
- FF/Latch Blocks:** Each block takes a data input (D) and produces a function output (F) and a carry output (CO). The carry input (CI) is also provided.
- LUT Expansion Mux:** A multiplexer that selects between the function outputs of the LUT4 & CARRY blocks and the FF/Latch blocks.

Outputs:

- To Routing:** OFX1, F1, Q1, OFX0, F0, Q0.
- FCI into Slice/PFU, FCO from Different Slice/PFU:** Signals entering and leaving the slice for configuration and control.

Note: some interslice signals not shown.

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0	Multipurpose Input
Input	Multi-purpose	M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FCI	Fast Carry In ¹
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register Outputs
Output	Data signals	OFX0	Output of a LUT5 MUX
Output	Data signals	OFX1	Output of a LUT6, LUT7, LUT8 ² MUX depending on the slice
Output	Inter-PFU signal	FCO	For the right most PFU the fast carry chain output ²

2. Requires two PFUs.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR 16x2 x 4 DPR 16x2 x 2	ROM 16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR 16x4 x 2 DPR 16x4 x 1	ROM 16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR 16x8 x 1	ROM 16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM 16x8 x1

Routing

There are many resources provided in the LatticeSC devices to route signals individually or as busses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

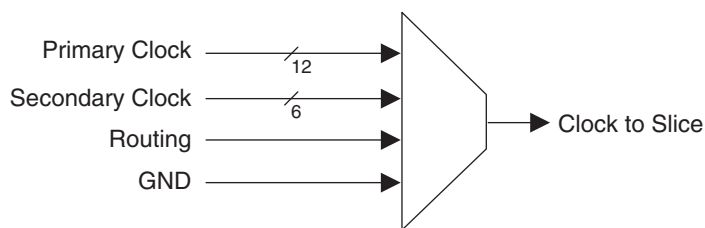
The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU) resources. The x1 and x2 connections provide fast and efficient connections in horizontal, vertical and diagonal directions. All connections are buffered to ensure high-speed operation even with long high-fanout connections.

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

sysCLOCK Network

The LatticeSC devices have three distinct clock networks for use in distributing high-performance clocks within the device: primary clocks, secondary clocks and edge clocks. In addition to these dedicated clock networks, users are free to route clocks within the device using the general purpose routing. Figure 2-4 shows the clock resources available to each slice.

Figure 2-4. Slice Clock Selection



Note: GND is available to switch off the network.

Primary Clock Sources

LatticeSC devices have a wide variety of primary clock sources available. Primary clocks sources consists of the following:

- Primary clock input pins
- Edge clock input pins
- Two outputs per DLL

Table 2-5. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36
True Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18
Pseudo Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36
FIFO	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1 and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Single, Dual and Pseudo-Dual Port Modes

In all the sysMEM RAM modes the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the output. A clock is required even in asynchronous read mode.

The EBR memory supports two forms of write behavior for dual port operation:

1. **Normal** — data on the output appears only during a read cycle. During a write cycle, the data (at the current address) does not appear on the output.
2. **Write Through** — a copy of the input data appears at the output of the same port.

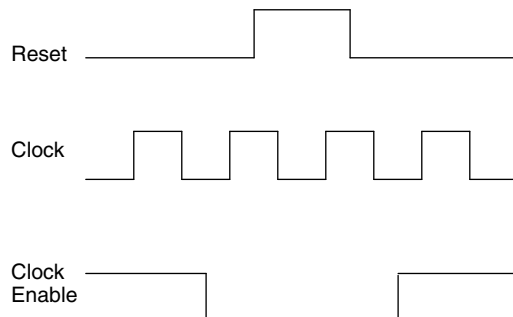
FIFO Configuration

The FIFO has a write port with Data-in, WCE, WE and WCLK signals. There is a separate read port with Data-out, RCE, RE and RCLK signals. The FIFO internally generates Almost Full, Full, Almost Empty, and Empty Flags. The Full and Almost Full flags are registered with WCLK. The Empty and Almost Empty flags are registered with RCLK.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the low-to-high transition of the reset, as shown in Figure 2-16.

Figure 2-16. EBR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becoming active.

These instructions apply to all EBR RAM, ROM, FIFO and shift register implementations. For the EBR FIFO mode, the GSR signal is always enabled and the WE and RE signals act like the clock enable signals in Figure 2-16. The reset timing rules apply to the RPRreset input vs. the RE input and the RST input vs. the WE and RE inputs. Both RST and RPRreset are always asynchronous EBR inputs. For the EBR shift register mode, the GSR signal is always enabled and the local RESET pin is always asynchronous.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled. For more information about on-chip memory, see TN1094, [On-Chip Memory Usage Guide for LatticeSC Devices](#).

Programmable I/O Cells (PIC)

Each PIC contains four PIOs connected to their respective PURESPEED I/O Buffer which are then connected to the PADs as shown in Figure 2-17. The PIO Block supplies the output data (DO) and the Tri-state control signal (TO) to PURESPEED I/O buffer, and receives input (DI) from the buffer. The PIO contains advanced capabilities to allow the support of speeds up to 2Gbps. These include dedicated shift and DDR logic and adaptive input logic. The dedicated resources simplify the design of robust interfaces.

Tristate Register Block

The tristate register block provides the ability to register tri-state control signals from the core of the device before they are passed to the PURESPEED I/O buffers. The block contains a register for SDR operation and a group of three registers for DDR and shift register operation. The output signal tri-state control signal (TO) can be derived directly from one of the inputs (bypass mode), the SDR shift register, the DDR registers or the data associated with the buffer (for open drain emulation). Figure 2-24 shows the diagram of the Tristate Register Block.

Tristate SDR Register/Latch Block

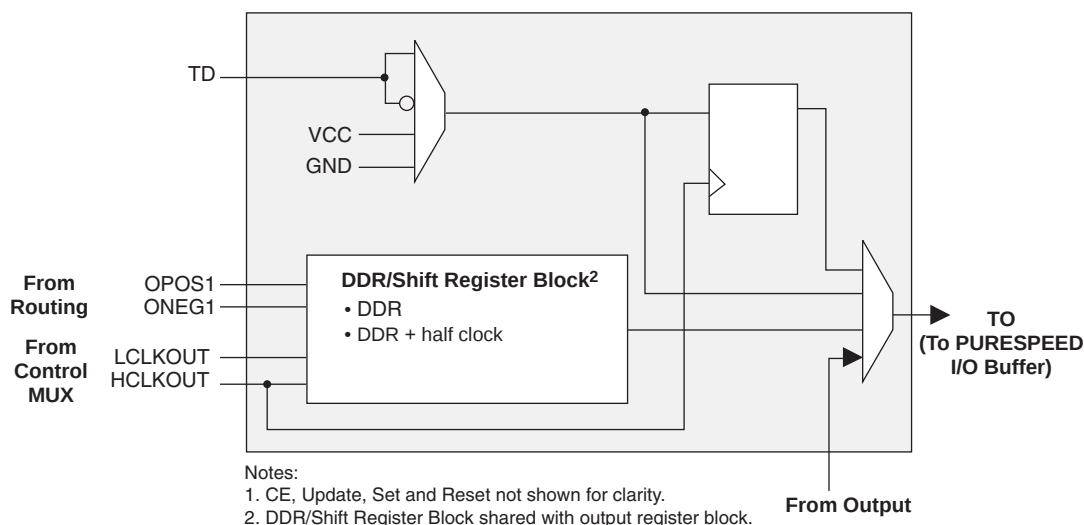
The SDR register operates on the positive edge of the high-speed clock. In it has a variety of programmable options for set/reset including, set or reset, asynchronous or synchronous Local Set Reset LSR and Global Set Reset GSR enable or disable. The register LSR input is driven from LSRO, which is generated from the PIO control MUX. The GSR input is driven from the GSR output of the PIO control MUX, which allows the global set-reset to be disabled on a PIO basis.

Tristate DDR/Shift Register Block

The DDR/Shift block is shared with the output block allowing DDR support using the high-speed clock and the associated transfer from the low-speed clock domain. It functions as a gearbox allowing low-speed parallel data from the FPGA fabric to provide a high-speed tri-state control stream.

There is a special mode for DDR-II memory interfaces where the termination is controlled by the output tristate signal. During WRITE cycle when the FPGA is driving the lines, the parallel terminations are turned off. During READ cycle when the FPGA is receiving data, the parallel terminations are turned on.

Figure 2-24. Tristate Register Block¹



I/O Architecture Rules

Table 2-6 shows the PIO usage for x1, x2, x4 gearing. The checkmarks in the columns show the specific PIOs that are used for each gearing mode. When using x2 or x4 gearing, any PIO which is not used for gearing can still be used as an output.

PCI Specification, Revision 2.2 requires the use of clamping diodes for 3.3V operation. For more information on the PCI interface, please refer to the PCI Specification, Revision 2.2.

Programmable Slew Rate Control

All output and bidirectional buffers have an optional programmable output slew rate control that can be configured for either low noise or high-speed performance. Each I/O pin has an individual slew rate control. This allows designers to specify slew rate control on a pin-by-pin basis. This slew rate control affects both the rising and falling edges.

Programmable Termination

Many of the I/O standards supported by the LatticeSC devices require termination at the transmitter, receiver or both. The SC devices provide the capability to implement many kinds of termination on-chip, minimizing stub lengths and hence improving performance. Utilizing this feature also has the benefit of reducing the number of discrete components required on the circuit board. The termination schemes can be split into two categories single-ended and differential.

Single Ended Termination

Single Ended Outputs: The SC devices support a number of different terminations for single ended outputs:

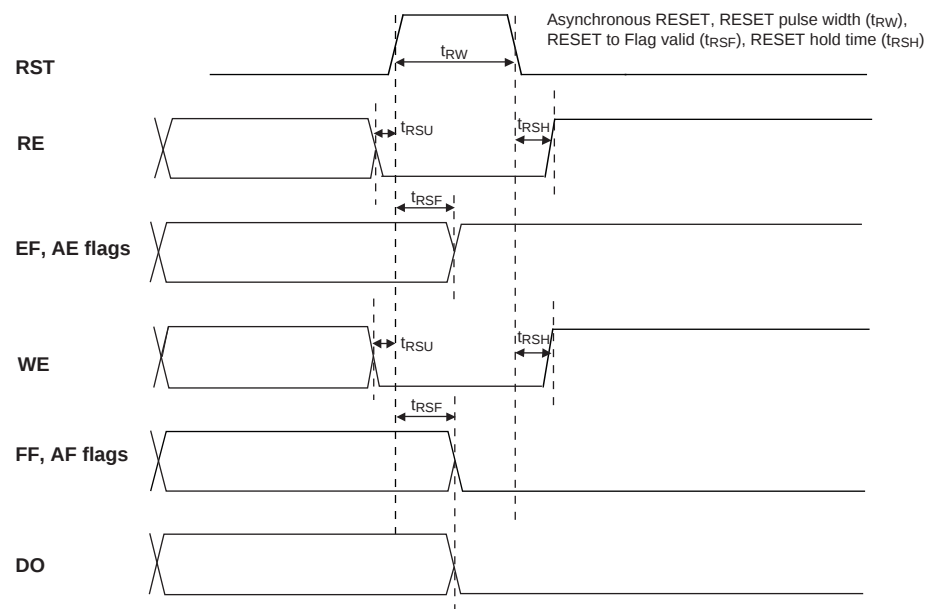
- Series
- Parallel to V_{CCIO} or GND
- Parallel to $V_{CCIO}/2$
- Parallel to $V_{CCIO}/2$ combined with series

Figure 2-27 shows the single ended output schemes that are supported. The nominal values of the termination resistors are shown in Table 2-10.

Density Shifting

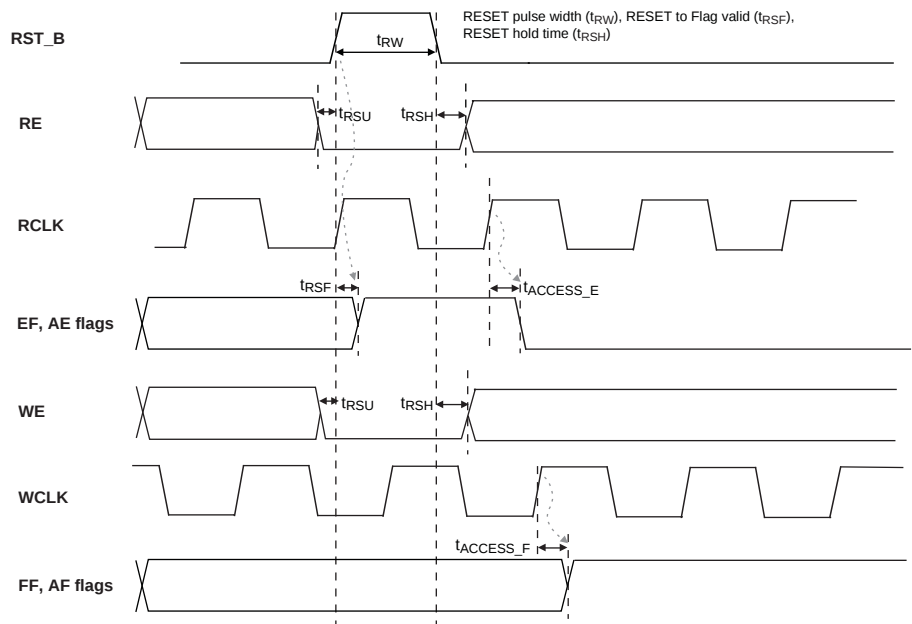
The LatticeSC family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

Figure 3-10. FIFO Reset Waveform



Note: RE and WE must be deactivated t_{RSU} before the Positive FIFO reset edge and enabled t_{RSH} after the FIFO reset negative edge.

Figure 3-11. Read Pointer Reset Waveform



Note: RE and WE must be deactivated t_{RSU} before the Positive FIFO reset edge and enabled t_{RSH} after the FIFO reset negative edge.

Pin Information Summary

Pin Type		256 fpBGA	900 fpBGA		1020 fcBGA	
		LFSC/M15	LFSC/M15	LFSC/M25	LFSC/M25	LFSC/M40
Single Ended User I/O		139	300	378	476	562
Differential Pair User I/O		60	141	182	235	277
LVDS Output Pairs		22	44	60	60	78
Configuration	Dedicated	9	11	11	11	11
	Muxes/MPI sysBus	0	55	55	55	72
JTAG (excluding VCCJ)		4	4	4	4	4
Dedicated Pins		2	4	4	4	4
VCC		10	46	46	40	40
VCC12		10	35	35	36	36
VCCAUX		10	36	36	32	32
VCCIO	Bank 1	3	18	18	10	10
	Bank 2	2	14	14	8	8
	Bank 3	2	15	15	10	10
	Bank 4	3	15	15	10	10
	Bank 5	3	15	15	10	10
	Bank 6	2	15	15	10	10
	Bank 7	2	16	16	8	8
VTT	Bank 2	0	2	2	2	2
	Bank 3	0	3	3	3	3
	Bank 4	0	3	3	3	3
	Bank 5	0	3	3	3	3
	Bank 6	0	3	3	3	3
	Bank 7	0	2	2	2	2
GND		26	177	177	134	134
NC		0	102	24	92	6
Single Ended User / Differential I/O per Bank	Bank 1	21/8	63/30	63/30	68/32	68/32
	Bank 2	15/7	26/13	30/15	34/17	54/27
	Bank 3	19/8	43/20	62/29	84/42	94/47
	Bank 4	25/11	50/22	66/32	84/41	99/48
	Bank 5	25/11	49/23	65/32	88/44	99/49
	Bank 6	19/8	43/20	62/29	84/42	94/47
	Bank 7	15/7	26/13	30/15	34/17	54/27
LVDS Output Pairs Per Bank	Bank 2	5	7	9	9	15
	Bank 3	6	15	21	21	24
	Bank 6	6	15	21	21	24
	Bank 7	5	7	9	9	15
VCCJ		1	1	1	1	1
SERDES (signal + power supply)		28	60	60	108	108
Total		256	900	900	1020	1152

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA^{1, 2} (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
B29	NC	-		NC	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).

2. The LatticeSC/M15 and LatticeSC/M25 in a 900-pin package supports a 16-bit MPI interface.

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
G6	A_HDINN2_R	-	PCS 3E0 CH 2 IN N	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
A6	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
D6	A_VDDOB2_R	-		A_VDDOB2_R	-	
B6	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
D7	A_VDDOB3_R	-		A_VDDOB3_R	-	
B7	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
A7	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
G7	A_HDINN3_R	-	PCS 3E0 CH 3 IN N	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
F7	A_HDINP3_R	-	PCS 3E0 CH 3 IN P	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
H7	A_VDDIB3_R	-		A_VDDIB3_R	-	
H8	B_VDDIB0_R	-		B_VDDIB0_R	-	
F8	B_HDINP0_R	-	PCS 3E1 CH 0 IN P	B_HDINP0_R	-	PCS 3E1 CH 0 IN P
G8	B_HDINN0_R	-	PCS 3E1 CH 0 IN N	B_HDINN0_R	-	PCS 3E1 CH 0 IN N
A8	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P
D8	B_VDDOB0_R	-		B_VDDOB0_R	-	
B8	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N
D9	B_VDDOB1_R	-		B_VDDOB1_R	-	
B9	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N
A9	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P
H10	B_HDINN1_R	-	PCS 3E1 CH 1 IN N	B_HDINN1_R	-	PCS 3E1 CH 1 IN N
G10	B_HDINP1_R	-	PCS 3E1 CH 1 IN P	B_HDINP1_R	-	PCS 3E1 CH 1 IN P
H9	B_VDDIB1_R	-		B_VDDIB1_R	-	
H11	B_VDDIB2_R	-		B_VDDIB2_R	-	
F11	B_HDINP2_R	-	PCS 3E1 CH 2 IN P	B_HDINP2_R	-	PCS 3E1 CH 2 IN P
G11	B_HDINN2_R	-	PCS 3E1 CH 2 IN N	B_HDINN2_R	-	PCS 3E1 CH 2 IN N
A11	B_HDOUTP2_R	-	PCS 3E1 CH 2 OUT P	B_HDOUTP2_R	-	PCS 3E1 CH 2 OUT P
D11	B_VDDOB2_R	-		B_VDDOB2_R	-	
B11	B_HDOUTN2_R	-	PCS 3E1 CH 2 OUT N	B_HDOUTN2_R	-	PCS 3E1 CH 2 OUT N
D12	B_VDDOB3_R	-		B_VDDOB3_R	-	
B12	B_HDOUTN3_R	-	PCS 3E1 CH 3 OUT N	B_HDOUTN3_R	-	PCS 3E1 CH 3 OUT N
A12	B_HDOUTP3_R	-	PCS 3E1 CH 3 OUT P	B_HDOUTP3_R	-	PCS 3E1 CH 3 OUT P
G12	B_HDINN3_R	-	PCS 3E1 CH 3 IN N	B_HDINN3_R	-	PCS 3E1 CH 3 IN N
F12	B_HDINP3_R	-	PCS 3E1 CH 3 IN P	B_HDINP3_R	-	PCS 3E1 CH 3 IN P
H12	B_VDDIB3_R	-		B_VDDIB3_R	-	
B10	VCC12	-		VCC12	-	
D10	B_REFCLKN_R	-		B_REFCLKN_R	-	
C10	B_REFCLKP_R	-		B_REFCLKP_R	-	
J15	PT49D	1	HDC/SI	PT61D	1	HDC/SI
K15	PT49C	1	LDCN/SCS	PT61C	1	LDCN/SCS
E13	PT49B	1	D8/MPI_DATA8	PT59B	1	D8/MPI_DATA8
F13	PT49A	1	CS1/MPI_CS1	PT59A	1	CS1/MPI_CS1
H13	PT47D	1	D9/MPI_DATA9	PT58D	1	D9/MPI_DATA9
G13	PT47C	1	D10/MPI_DATA10	PT58C	1	D10/MPI_DATA10
E14	PT47B	1	CS0N/MPI_CS0N	PT57B	1	CS0N/MPI_CS0N
F14	PT47A	1	RDN/MPI_STRB_N	PT57A	1	RDN/MPI_STRB_N
H14	PT46D	1	WRN/MPI_WR_N	PT55D	1	WRN/MPI_WR_N
G14	PT46C	1	D7/MPI_DATA7	PT55C	1	D7/MPI_DATA7
D13	PT46B	1	D6/MPI_DATA6	PT55B	1	D6/MPI_DATA6
D14	PT46A	1	D5/MPI_DATA5	PT55A	1	D5/MPI_DATA5
E15	PT45D	1	D4/MPI_DATA4	PT54D	1	D4/MPI_DATA4

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
E16	PT45C	1	D3/MPI_DATA3	PT54C	1	D3/MPI_DATA3
C13	PT45B	1	D2/MPI_DATA2	PT53B	1	D2/MPI_DATA2
C14	PT45A	1	D1/MPI_DATA1	PT53A	1	D1/MPI_DATA1
B14	PT43B	1	D0/MPI_DATA0	PT51B	1	D0/MPI_DATA0
B13	PT43A	1	QOUT/CEON	PT51A	1	QOUT/CEON
L13	PT42D	1	VREF2_1	PT50D	1	VREF2_1
C15	PT42B	1	DOUT	PT50B	1	DOUT
D15	PT42A	1	MCA_DONE_IN	PT50A	1	MCA_DONE_IN
J16	PT41B	1	MCA_CLK_P1_OUT	PT49B	1	MCA_CLK_P1_OUT
K16	PT41A	1	MCA_CLK_P1_IN	PT49A	1	MCA_CLK_P1_IN
H15	PT39D	1	D21/PCLKC1_1/MPI_DATA21	PT47D	1	D21/PCLKC1_1/MPI_DATA21
H16	PT39C	1	D22/PCLKT1_1/MPI_DATA22	PT47C	1	D22/PCLKT1_1/MPI_DATA22
A14	PT39B	1	MCA_CLK_P2_OUT	PT47B	1	MCA_CLK_P2_OUT
A13	PT39A	1	MCA_CLK_P2_IN	PT47A	1	MCA_CLK_P2_IN
G16	PT38D	1	MCA_DONE_OUT	PT46D	1	MCA_DONE_OUT
F16	PT38C	1	BUSYN/RCLK/SCK	PT46C	1	BUSYN/RCLK/SCK
B16	PT38B	1	DP0/MPI_PAR0	PT46B	1	DP0/MPI_PAR0
B15	PT38A	1	MPI_TA	PT46A	1	MPI_TA
L16	PT37C	1	DP2/MPI_PAR2	PT45C	1	DP2/MPI_PAR2
A16	PT37B	1	PCLKC1_0	PT45B	1	PCLKC1_0
A15	PT37A	1	PCLKT1_0/MPI_CLK	PT45A	1	PCLKT1_0/MPI_CLK
L17	PT35C	1	D24/PCLKT1_4/MPI_DATA24	PT43C	1	D24/PCLKT1_4/MPI_DATA24
A17	PT35B	1	MPI_RETRY	PT43B	1	MPI_RETRY
A18	PT35A	1	A0/MPI_ADDR14	PT43A	1	A0/MPI_ADDR14
F17	PT33D	1	A1/MPI_ADDR15	PT42D	1	A1/MPI_ADDR15
G17	PT33C	1	A2/MPI_ADDR16	PT42C	1	A2/MPI_ADDR16
B17	PT33B	1	A3/MPI_ADDR17	PT42B	1	A3/MPI_ADDR17
B18	PT33A	1	A4/MPI_ADDR18	PT42A	1	A4/MPI_ADDR18
H17	PT32D	1	D25/PCLKC1_5/MPI_DATA25	PT41D	1	D25/PCLKC1_5/MPI_DATA25
H18	PT32C	1	D26/PCLKT1_5/MPI_DATA26	PT41C	1	D26/PCLKT1_5/MPI_DATA26
A19	PT32B	1	A5/MPI_ADDR19	PT41B	1	A5/MPI_ADDR19
A20	PT32A	1	A6/MPI_ADDR20	PT41A	1	A6/MPI_ADDR20
L20	PT31C	1	VREF1_1	PT39C	1	VREF1_1
J17	PT31B	1	A7/MPI_ADDR21	PT39B	1	A7/MPI_ADDR21
K17	PT31A	1	A8/MPI_ADDR22	PT39A	1	A8/MPI_ADDR22
C18	PT29B	1	A9/MPI_ADDR23	PT38B	1	A9/MPI_ADDR23
D18	PT29A	1	A10/MPI_ADDR24	PT38A	1	A10/MPI_ADDR24
B19	PT28B	1	A11/MPI_ADDR25	PT37B	1	A11/MPI_ADDR25
B20	PT28A	1	A12/MPI_ADDR26	PT37A	1	A12/MPI_ADDR26
E17	PT27D	1	D11/MPI_DATA11	PT35D	1	D11/MPI_DATA11
E18	PT27C	1	D12/MPI_DATA12	PT35C	1	D12/MPI_DATA12
C20	PT27B	1	A13/MPI_ADDR27	PT35B	1	A13/MPI_ADDR27
C19	PT27A	1	A14/MPI_ADDR28	PT35A	1	A14/MPI_ADDR28
H19	PT25D	1	A16/MPI_ADDR30	PT33D	1	A16/MPI_ADDR30
G19	PT25C	1	D13/MPI_DATA13	PT33C	1	D13/MPI_DATA13
D20	PT25B	1	A15/MPI_ADDR29	PT33B	1	A15/MPI_ADDR29
D19	PT25A	1	A17/MPI_ADDR31	PT33A	1	A17/MPI_ADDR31
H20	PT24D	1	A19/MPI_TSI21	PT30D	1	A19/MPI_TSI21
G20	PT24C	1	A20/MPI_BDIP	PT30C	1	A20/MPI_BDIP
E19	PT24B	1	A18/MPI_TSI20	PT30B	1	A18/MPI_TSI20

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
V25	PL44C	6		PL56C	6	
W25	PL44D	6		PL56D	6	
U34	PL45A	6		PL57A	6	
V34	PL45B	6		PL57B	6	
V26	PL45C	6		PL57C	6	
W26	PL45D	6		PL57D	6	
V33	PL47A	6		PL60A	6	
W33	PL47B	6		PL60B	6	
V24	PL47C	6		PL60C	6	
W24	PL47D	6		PL60D	6	
W31	PL48A	6		PL63A	6	
Y31	PL48B	6		PL63B	6	
Y29	PL48C	6		PL63C	6	
AA29	PL48D	6		PL63D	6	
Y33	PL49A	6		PL65A	6	
AA33	PL49B	6		PL65B	6	
Y28	PL49C	6		PL65C	6	
AA28	PL49D	6		PL65D	6	
AB32	PL51A	6		PL76A	6	
AC32	PL51B	6		PL76B	6	
AA26	PL51C	6		PL76C	6	
AA27	PL51D	6	DIFFR_6	PL76D	6	DIFFR_6
AB31	PL52A	6		PL77A	6	
AC31	PL52B	6		PL77B	6	
Y24	PL52C	6		PL77C	6	
AA24	PL52D	6		PL77D	6	
AE34	PL53A	6		PL78A	6	
AF34	PL53B	6		PL78B	6	
AB30	PL53C	6		PL78C	6	
AC30	PL53D	6		PL78D	6	
AD33	PL56A	6		PL80A	6	
AE33	PL56B	6		PL80B	6	
AD30	PL56C	6		PL80C	6	
AE30	PL56D	6		PL80D	6	
AE32	PL57A	6		PL81A	6	
AF32	PL57B	6		PL81B	6	
AA25	PL57C	6		PL81C	6	
AB25	PL57D	6		PL81D	6	
AJ34	PL58A	6		PL82A	6	
AK34	PL58B	6		PL82B	6	
AB27	PL58C	6		PL82C	6	
AC27	PL58D	6		PL82D	6	
AF33	PL60A	6		PL84A	6	
AG33	PL60B	6		PL84B	6	
AC29	PL60C	6		PL84C	6	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
D7	B_VDDIB0_R	-		B_VDDIB0_R	-	
E10	B_HDINP0_R	-	PCS 3E1 CH 0 IN P	B_HDINP0_R	-	PCS 3E1 CH 0 IN P
F10	B_HDINN0_R	-	PCS 3E1 CH 0 IN N	B_HDINN0_R	-	PCS 3E1 CH 0 IN N
K10	VCC12	-		VCC12	-	
A11	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P
D10	B_VDDOB0_R	-		B_VDDOB0_R	-	
B11	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N
D11	B_VDDOB1_R	-		B_VDDOB1_R	-	
B12	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N
L10	VCC12	-		VCC12	-	
A12	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P
F11	B_HDINN1_R	-	PCS 3E1 CH 1 IN N	B_HDINN1_R	-	PCS 3E1 CH 1 IN N
E11	B_HDINP1_R	-	PCS 3E1 CH 1 IN P	B_HDINP1_R	-	PCS 3E1 CH 1 IN P
G11	VCC12	-		VCC12	-	
D8	B_VDDIB1_R	-		B_VDDIB1_R	-	
G12	VCC12	-		VCC12	-	
D9	B_VDDIB2_R	-		B_VDDIB2_R	-	
E12	B_HDINP2_R	-	PCS 3E1 CH 2 IN P	B_HDINP2_R	-	PCS 3E1 CH 2 IN P
F12	B_HDINN2_R	-	PCS 3E1 CH 2 IN N	B_HDINN2_R	-	PCS 3E1 CH 2 IN N
K11	VCC12	-		VCC12	-	
A13	B_HDOUTP2_R	-	PCS 3E1 CH 2 OUT P	B_HDOUTP2_R	-	PCS 3E1 CH 2 OUT P
D12	B_VDDOB2_R	-		B_VDDOB2_R	-	
B13	B_HDOUTN2_R	-	PCS 3E1 CH 2 OUT N	B_HDOUTN2_R	-	PCS 3E1 CH 2 OUT N
D13	B_VDDOB3_R	-		B_VDDOB3_R	-	
B14	B_HDOUTN3_R	-	PCS 3E1 CH 3 OUT N	B_HDOUTN3_R	-	PCS 3E1 CH 3 OUT N
L11	VCC12	-		VCC12	-	
A14	B_HDOUTP3_R	-	PCS 3E1 CH 3 OUT P	B_HDOUTP3_R	-	PCS 3E1 CH 3 OUT P
F13	B_HDINN3_R	-	PCS 3E1 CH 3 IN N	B_HDINN3_R	-	PCS 3E1 CH 3 IN N
E13	B_HDINP3_R	-	PCS 3E1 CH 3 IN P	B_HDINP3_R	-	PCS 3E1 CH 3 IN P
G13	VCC12	-		VCC12	-	
E9	B_VDDIB3_R	-		B_VDDIB3_R	-	
L13	VCC12	-		VCC12	-	
J11	B_REFCLKN_R	-		B_REFCLKN_R	-	
H11	B_REFCLKP_R	-		B_REFCLKP_R	-	
M15	PT61D	1	HDC/SI	PT77D	1	HDC/SI
M16	PT61C	1	LDCN/SCS	PT77C	1	LDCN/SCS
F14	PT59B	1	D8/MPI_DATA8	PT77B	1	D8/MPI_DATA8
G14	PT59A	1	CS1/MPI_CS1	PT77A	1	CS1/MPI_CS1
L15	PT58D	1	D9/MPI_DATA9	PT75D	1	D9/MPI_DATA9
L14	PT58C	1	D10/MPI_DATA10	PT75C	1	D10/MPI_DATA10
D14	PT57B	1	CS0N/MPI_CS0N	PT75B	1	CS0N/MPI_CS0N
E14	PT57A	1	RDN/MPI_STRB_N	PT75A	1	RDN/MPI_STRB_N
L16	PT55D	1	WRN/MPI_WR_N	PT74D	1	WRN/MPI_WR_N
K16	PT55C	1	D7/MPI_DATA7	PT74C	1	D7/MPI_DATA7
G15	PT55B	1	D6/MPI_DATA6	PT74B	1	D6/MPI_DATA6

LFSC/M115 Logic Signal Connections: 1152 fcBGA^{1, 2}

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
W30	PL69B	6	VREF1_6
W27	PL69C	6	
Y27	PL69D	6	
T33	PL70A	6	
U33	PL70B	6	
V25	PL70C	6	
W25	PL70D	6	
U34	PL71A	6	
V34	PL71B	6	
V26	PL71C	6	
W26	PL71D	6	
V33	PL74A	6	
W33	PL74B	6	
V24	PL74C	6	
W24	PL74D	6	
W31	PL77A	6	
Y31	PL77B	6	
Y29	PL77C	6	
AA29	PL77D	6	
Y33	PL79A	6	
AA33	PL79B	6	
Y28	PL79C	6	
AA28	PL79D	6	
AB32	PL90A	6	
AC32	PL90B	6	
AA26	PL90C	6	
AA27	PL90D	6	
AB31	PL91A	6	DIFFR_6
AC31	PL91B	6	
Y24	PL91C	6	
AA24	PL91D	6	
AE34	PL92A	6	
AF34	PL92B	6	
AB30	PL92C	6	
AC30	PL92D	6	
AD33	PL94A	6	
AE33	PL94B	6	
AD30	PL94C	6	
AE30	PL94D	6	
AE32	PL96A	6	
AF32	PL96B	6	
AA25	PL96C	6	
AB25	PL96D	6	

LFSC/M115 Logic Signal Connections: 1152 fcBGA^{1, 2}

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AL5	GND	-	
AM14	GND	-	
AM18	GND	-	
AM24	GND	-	
AM30	GND	-	
AM8	GND	-	
AN1	GND	-	
AN34	GND	-	
AP2	GND	-	
AP33	GND	-	
B1	GND	-	
B34	GND	-	
C11	GND	-	
C12	GND	-	
C13	GND	-	
C14	GND	-	
C17	GND	-	
C21	GND	-	
C22	GND	-	
C23	GND	-	
C24	GND	-	
C26	GND	-	
C27	GND	-	
C30	GND	-	
C31	GND	-	
C4	GND	-	
C5	GND	-	
C8	GND	-	
C9	GND	-	
D18	GND	-	
E32	GND	-	
E4	GND	-	
F19	GND	-	
G16	GND	-	
G29	GND	-	
G7	GND	-	
H3	GND	-	
H31	GND	-	
J10	GND	-	
J15	GND	-	
J26	GND	-	
K20	GND	-	
K23	GND	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AV32	PB27B	5		PB29B	5	
AU36	PB27C	5		PB29C	5	
AU37	PB27D	5		PB29D	5	
BA35	PB28A	5		PB30A	5	
BA34	PB28B	5		PB30B	5	
AJ26	PB28C	5		PB30C	5	
AJ27	PB28D	5		PB30D	5	
AW33	PB29A	5		PB31A	5	
AW32	PB29B	5		PB31B	5	
AU35	PB29C	5		PB31C	5	
AU34	PB29D	5		PB31D	5	
BB35	PB31A	5		PB33A	5	
BB34	PB31B	5		PB33B	5	
AN29	PB31C	5		PB33C	5	
AP29	PB31D	5		PB33D	5	
AY33	PB32A	5		PB34A	5	
AY32	PB32B	5		PB34B	5	
AR31	PB32C	5		PB34C	5	
AR30	PB32D	5		PB34D	5	
AV31	PB33A	5		PB35A	5	
AV30	PB33B	5		PB35B	5	
AN28	PB33C	5		PB35C	5	
AP28	PB33D	5		PB35D	5	
BA33	PB35A	5		PB37A	5	
BA32	PB35B	5		PB37B	5	
AT30	PB35C	5		PB37C	5	
AT31	PB35D	5		PB37D	5	
BB33	PB36A	5		PB38A	5	
BB32	PB36B	5		PB38B	5	
AM26	PB36C	5		PB38C	5	
AL26	PB36D	5		PB38D	5	
AW30	PB37A	5		PB39A	5	
AW29	PB37B	5		PB39B	5	
AP27	PB37C	5		PB39C	5	
AN27	PB37D	5		PB39D	5	
BA31	PB39A	5		PB41A	5	
BA30	PB39B	5		PB41B	5	
AU32	PB39C	5		PB41C	5	
AU33	PB39D	5		PB41D	5	
BB31	PB40A	5		PB42A	5	
BB30	PB40B	5		PB42B	5	
AR28	PB40C	5		PB42C	5	
AR27	PB40D	5		PB42D	5	
AV29	PB41A	5		PB43A	5	
AV28	PB41B	5		PB43B	5	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
V21	VCC	-		VCC	-	
V22	VCC	-		VCC	-	
V23	VCC	-		VCC	-	
V25	VCC	-		VCC	-	
V27	VCC	-		VCC	-	
W17	VCC	-		VCC	-	
W19	VCC	-		VCC	-	
W21	VCC	-		VCC	-	
W22	VCC	-		VCC	-	
W24	VCC	-		VCC	-	
W26	VCC	-		VCC	-	
Y16	VCC	-		VCC	-	
Y18	VCC	-		VCC	-	
Y20	VCC	-		VCC	-	
Y23	VCC	-		VCC	-	
Y25	VCC	-		VCC	-	
Y27	VCC	-		VCC	-	
AG22	VCC12	-		VCC12	-	
AG26	VCC12	-		VCC12	-	
T17	VCC12	-		VCC12	-	
T21	VCC12	-		VCC12	-	
T22	VCC12	-		VCC12	-	
T26	VCC12	-		VCC12	-	
U16	VCC12	-		VCC12	-	
U27	VCC12	-		VCC12	-	
AC15	VCCAUX	-		VCCAUX	-	
AC28	VCCAUX	-		VCCAUX	-	
AD15	VCCAUX	-		VCCAUX	-	
AD28	VCCAUX	-		VCCAUX	-	
AE15	VCCAUX	-		VCCAUX	-	
AE28	VCCAUX	-		VCCAUX	-	
AF15	VCCAUX	-		VCCAUX	-	
AF28	VCCAUX	-		VCCAUX	-	
AG15	VCCAUX	-		VCCAUX	-	
AG28	VCCAUX	-		VCCAUX	-	
AH14	VCCAUX	-		VCCAUX	-	
AH16	VCCAUX	-		VCCAUX	-	
AH17	VCCAUX	-		VCCAUX	-	
AH18	VCCAUX	-		VCCAUX	-	
AH19	VCCAUX	-		VCCAUX	-	
AH20	VCCAUX	-		VCCAUX	-	
AH23	VCCAUX	-		VCCAUX	-	
AH24	VCCAUX	-		VCCAUX	-	
AH25	VCCAUX	-		VCCAUX	-	
AH26	VCCAUX	-		VCCAUX	-	

Industrial

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA15E-6F256I	-6	fpBGA	256	IND	15.2
LFSC3GA15E-5F256I	-5	fpBGA	256	IND	15.2
LFSC3GA15E-6F900I	-6	fpBGA	900	IND	15.2
LFSC3GA15E-5F900I	-5	fpBGA	900	IND	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA15EP1-6F256I	-6	fpBGA	256	IND	15.2
LFSCM3GA15EP1-5F256I	-5	fpBGA	256	IND	15.2
LFSCM3GA15EP1-6F900I	-6	fpBGA	900	IND	15.2
LFSCM3GA15EP1-5F900I	-5	fpBGA	900	IND	15.2

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA25E-6F900I	-6	fpBGA	900	IND	25.4
LFSC3GA25E-5F900I	-5	fpBGA	900	IND	25.4
LFSC3GA25E-6FF1020I ¹	-6	Organic fcBGA	1020	IND	25.4
LFSC3GA25E-5FF1020I ¹	-5	Organic fcBGA	1020	IND	25.4
LFSC3GA25E-6FFA1020I	-6	Organic fcBGA Revision 2	1020	IND	25.4
LFSC3GA25E-5FFA1020I	-5	Organic fcBGA Revision 2	1020	IND	25.4

1. Converted to organic flip-chip BGA package revision 2 per [PCN #02A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA25EP1-6F900I	-6	fpBGA	900	IND	25.4
LFSCM3GA25EP1-5F900I	-5	fpBGA	900	IND	25.4
LFSCM3GA25EP1-6FF1020I ¹	-6	Organic fcBGA	1020	IND	25.4
LFSCM3GA25EP1-5FF1020I ¹	-5	Organic fcBGA	1020	IND	25.4
LFSCM3GA25EP1-6FFA1020I	-6	Organic fcBGA Revision 2	1020	IND	25.4
LFSCM3GA25EP1-5FFA1020I	-5	Organic fcBGA Revision 2	1020	IND	25.4

1. Converted to organic flip-chip BGA package revision 2 per [PCN #02A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA40E-6FF1020I ¹	-6	Organic fcBGA	1020	IND	40.4
LFSC3GA40E-5FF1020I ¹	-5	Organic fcBGA	1020	IND	40.4
LFSC3GA40E-6FFA1020I	-6	Organic fcBGA Revision 2	1020	IND	40.4
LFSC3GA40E-5FFA1020I	-5	Organic fcBGA Revision 2	1020	IND	40.4
LFSC3GA40E-6FC1152I ²	-6	Ceramic fcBGA	1152	IND	40.4
LFSC3GA40E-5FC1152I ²	-5	Ceramic fcBGA	1152	IND	40.4
LFSC3GA40E-6FF1152I	-6	Organic fcBGA	1152	IND	40.4
LFSC3GA40E-5FF1152I	-5	Organic fcBGA	1152	IND	40.4

1. Converted to organic flip-chip BGA package revision 2 per [PCN #02A-10](#).

2. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Date	Version	Section	Change Summary
June 2006 (cont.)	01.2 (cont.)	DC and Switching Characteristics (cont.)	Updated Typical Building Block Performance with ispLEVER 6.0 values.
			Updated LatticeSC External Switching Characteristics with ispLEVER 6.0 values.
			Updated Lattice SC Internal Timing Parameters with ispLEVER 6.0 values.
			Updated Lattice SC Family Timing Adders with ispLEVER 6.0 values
			Changed % spread from 1 to 0.5 min and from 3 to 1.5 max.
			Changed conditions to refer to “with multiplication” and “without multiplication”.
			Changed the formula for t_{OPJIT} with multiplication (same result, different representation).
		Pinout Information	Expanded definition of NC.
			Expanded definition of GND.
			Expanded definition of VTT_x.
			Expanded definition of VCC12.
			Added accuracy of TEMP pin.
			Added RESPN_[ULC/URC].
			Updated Pin Information Summary with additional devices and packages.
			Added additional devices and packages pinouts.
			Removed Power Supply and NC connections table
			Removed VTT table
			Removed LFSC25 Logic Signal Connections: 900-Ball fBGA1 table
			Changed all VDDP, VDDTX and VDDR _X to VCC12.
		Ordering Information	Added dual marking.
			Added lead free packaging information to part number description.
August 2006	01.3	Introduction	Added SC40 1152 information to Table 1-1.
			Updated Table 1-3 with ispLEVER 6.0 SP1 results.
		Architecture	Added SSTL18 II to Table 2-8.
			Changed Table 2-10 VCCIO column to “N/A” for LVDS, mini-LVDS, BLVDS25, MLVDS25, HYPT and RSDS.
			Changed Hypertransport performance to 700 MHz (1400 Mbps) in Table 2-11.
			Changed SPI4.2 performance to 500 MHz (1000 Mbps) in Table 2-11
			Added “On packages that include PROBE_GND, the most accurate measurements will occur between the TEMP pin and the PROBE_GND pin. On packages that do not include PROBE_GND, measurements should be made between the TEMP pin and board ground.”
			Added VCCIO of 2.5 V for LVPECL33 in table 2-9.
		DC and Switching Characteristics	Updated Typical Building Block Performance with ispLEVER 6.0 SP1 results.
			Updated Initialization and Standby Supply Current table to break out ICC and ICC12.
			Updated LatticeSC External Switching Characteristics with ispLEVER 6.0 SP1 results.
			Updated LatticeSC Internal Timing Parameters with ispLEVER 6.0 SP1 results.